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TI Cladding materials for **sputtering targets**
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SO Jpn. Kokai Tokkyo Koho, 3 pp.

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AB The material is made of **Cu** >99.7%, and Zn, In, Mn, Sb, Be, Ca, Cr, Te, Y, Nb, Mo, Ta, and/or **Sn** 100-3000 ppm for separation of the backing plate in exchange of the **target** and efficient cooling.